Silicon P-Channel MOS FET

HITACHI

ADE-208-382 1st. Edition

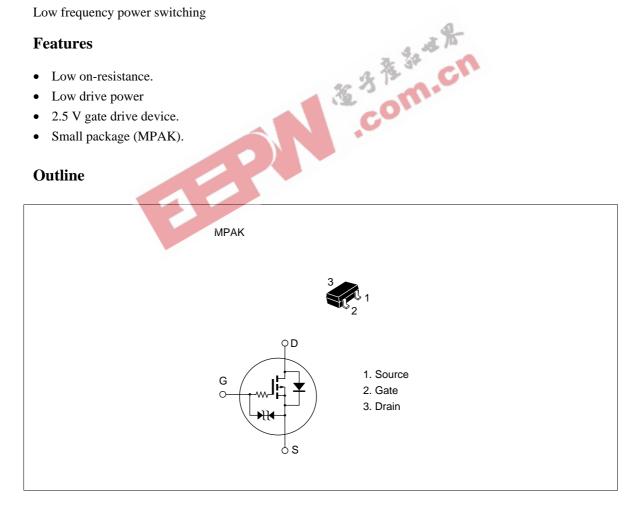
Application

Low frequency power switching

Features

- Low on-resistance.
- Low drive power
- 2.5 V gate drive device.
- Small package (MPAK).

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

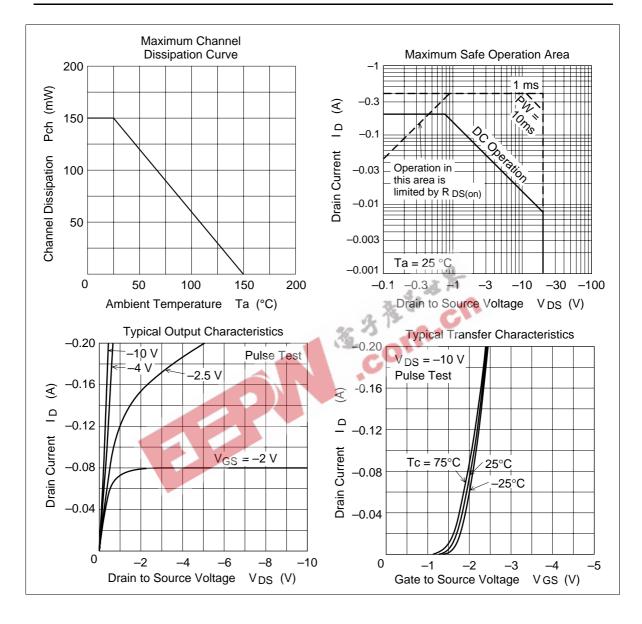
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-20	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	-0.2	А
Drain peak current	l _{D(pulse)} *1	-0.4	А
Channel dissipation	Pch	150	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

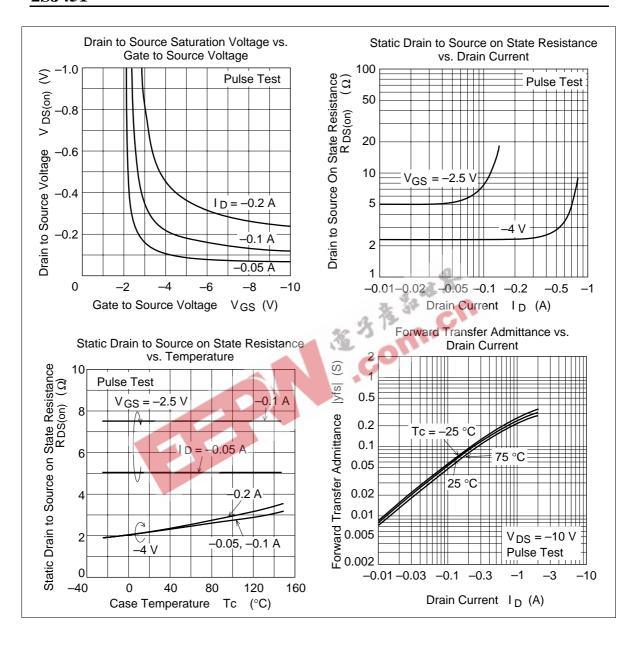
Note: 1. PW \leq 10 μ s, duty cycle \leq 1% Marking is "ZK-".

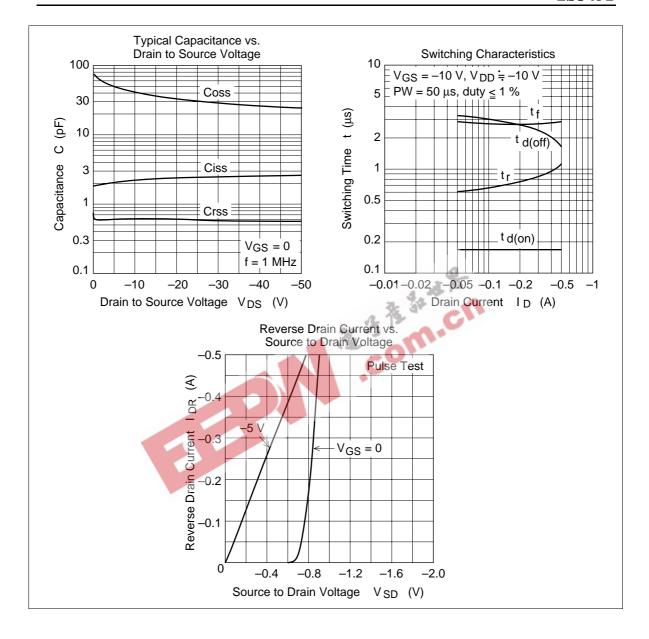
Electrical Characteristics ($Ta = 25^{\circ}C$)

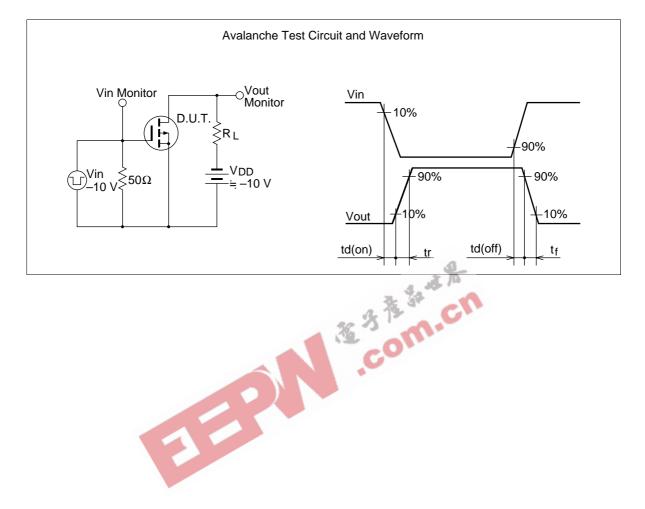
Marking is ZK					4	
				26.	如此月	•
Electrical Characteristics ($Ta = 25$ °C)			Typ Max Unit Test conditions			
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-20		*C.	V	$I_D = -100 \ \mu A, \ V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20		_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		_	-1.0	μΑ	$V_{DS} = -16 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±2.0	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{\rm GS(off)}$	-0.5	_	-1.5	V	$I_D = -10 \mu A, V_{DS} = -5 V$
Static drain to source on state resistance	$R_{\text{DS(on)}}1$	_	2.3	3.5	Ω	$I_D = -100 \text{ mA}$ $V_{GS} = -4 \text{ V}^{*1}$
Static drain to source on state resistance	$R_{\text{DS(on)}}2$	_	5.0	9.0	Ω	$I_D = -40 \text{ mA}$ $V_{GS} = -2.5 \text{ V}^{*1}$
Foward transfer admittance	$ y_{fs} $	0.13	0.23	_	S	$I_D = -100 \text{ mA}^{*1}$ $V_{DS} = -10 \text{ V}$
Input capacitance	Ciss	_	2.4	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	31	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	0.6	_	pF	f = 1 MHz
Turn-on delay time	$t_{\scriptsize d(on)}$	_	0.17	_	μs	$V_{GS} = -10 \text{ V}, I_{D} = -0.1 \text{ A}$
Rise time	t _r	_	0.68	_	μs	$R_L = 100 \Omega$
Turn-off delay time	$t_{\text{d(off)}}$	_	3.0	_	μs	_
Fall time	t_{f}	_	2.8	_	μs	

Note: 1. Pulse Test



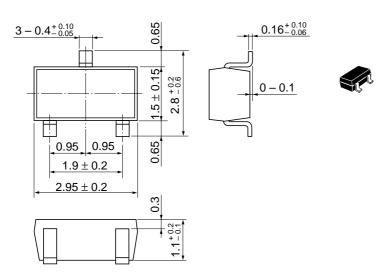








Unit: mm



Hitachi Code	MPAK
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.011 a

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